Technical Data Sheet

● Product Description:

- Two component silicone addition type potting compound
- Low viscosity, good fluidity, easy to operate
- Glue can store a long time after mixing at room temperature,It can be cured quickly under heating condition, especially for automatic production line
- Good temperature resistance, it can maintain rubber elasticity in a wide temperature range（-50～200℃）after cured
- Good thermal conductivity, excellent insulation performance
- The curing process does not shrink, has better waterproof and moisture resistance and anti-aging performance
- Comply with EU ROHS directive requirements

●Product Application:

• It can use in the high power electronic components, modular power supplies and circuit boards for potting protection,which has good heat conduction and temperature resistance. Such as LED driving power ,automotive HID lamp module power supply, automotive ignition system module power supply, network transformers, etc.

●Product Instruction:

- Before use, the A component and B component in their respective containers fully mixing evenly, and then according to the weight ratio of A:B=1:1, put into the mixing tank mixing evenly
- Put the mixture into the container. Curing at room temperature or heating. In the winter, it will take a long time to cure, suggested by heating curing, curing under 80℃ for 15-30 minutes , and at room temperature, generally takes about 3~5 hours curing.

•Caution:

- Glue should be sealed storage. The mixture should be used once to avoid waste
- This product is not dangerous, but do not eat and into the eyes.
- After a long period of storage, there will be precipitation in the glue. Please mix evenly to use and does not affect the performance
- Glue exposure to a certain amount of the following chemical substances will make the glue does not solidify (little amount of the following substances will not affect the curing)
  - N, P, S organic compounds
  - Ionic compounds of Sn, Pb, Hg, As and other elements
  - Containing alkynes and vinyl compounds
  - In order to avoid the above phenomenon, the use of the circuit board as far as possible to wipe clean the remaining rosin, try to use low lead content of solder. It can also use three anti - paint soaked, and then use glue

● Technical Specification：PS-6401

Before Mixing（ 25℃，65%RH）		
Component	A	B
Colour	White fluid	Black fluid
Viscosity (cP)	2600-3200	2600-3200
Density（g/ml）	1.66±0. 02	1.66±0. 02
After Mixing（ 25℃，65%RH）		
Mixing ratio (weight ratio)	A：B = 1 ： 1	
Colour	Grey	
Viscosity (CP)	2600-3200	
Operating time (min)	60-120	
Curing time（25℃，h）	2-4	
Curing time（min，80℃）	10～20	
Hardness (shore A)	50-60	
Thermal conductivity W（m·K）	0.9±0.1	
Dielectric strength (kV/mm)	≥14	
Dielectric constant (1.2MHz)	2.8～3.3	
Volume resistivity（Ω·cm）	≥1.86×10^{14}	

* Viscosity, curing time can be adjusted according to user requirements

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•Packing Specification：

·50Kg/ sets

•Storage And Transport

• This product storage period of six months（25℃）.

• Such products are non hazardous and can be transported in general chemicals

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